



Material Content Data Sheet



Sales Product Name				IAUC100N04S6L014		Issued		30. July 2019	
MA#				MA001701714					
Package				PG-TDSON-8-34		Weight*		112.43 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.821	0.73	0.73	7300	7300	
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141		
	non noble metal	iron	7439-89-6	0.053	0.05		471		
	non noble metal	copper	7440-50-8	52.842	46.98	47.04	470016	470628	
	noble metal	gold	7440-57-5	0.044	0.04	0.04	391	391	
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	391	391	
encapsulation	organic material	carbon black	1333-86-4	0.076	0.07		674		
	plastics	epoxy resin	-	5.990	5.33		53280		
	inorganic material	silicondioxide	60676-86-0	31.846	28.33	33.73	283260	337214	
leadfinish	non noble metal	tin	7440-31-5	1.574	1.40	1.40	13999	13999	
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1861	1861	
solder	non noble metal	tin	7440-31-5	0.023	0.02		206		
	noble metal	silver	7440-22-4	0.029	0.03		257		
	non noble metal	lead	7439-92-1	1.105	0.98	1.03	9831	10294	
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	iron	7439-89-6	0.017	0.02		150		
	non noble metal	copper	7440-50-8	16.828	14.97	14.99	149677	149872	
clip plating	noble metal	silver	7440-22-4	0.639	0.57	0.57	5684	5684	
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	iron	7439-89-6	0.000	0.00		3		
	non noble metal	copper	7440-50-8	0.310	0.28	0.28	2753	2757	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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